



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31C270FBCNNNC
- Description : CAP, 27pF, 50V, ±1%, C0G, 1206

A. Samsung Part Number

	<u>CL</u>	<u>31</u> C		E	B	<u>C</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>C</u>
	(1)	23) (4)	(5)	6		8	9	10	(\mathfrak{b})
1 Series	Samsung Multi-la	ayer Cera	amic Cap	acito	or					
② Size	1206 (inch co	ode)	L:	3.2	± 0.′	15	mm		W:	1.6 ± 0.15 mm
	000									NI:
③ Dielectric	COG			(8)	Inne	r ele	ctroc	le		Ni
Capacitance	27 pF				Terr	ninat	tion			Cu
⑤ Capacitance	±1 %				Plat	ing				Sn 100% (Pb Free)
tolerance				9	Proc	duct				Normal
⑥ Rated Voltage	50 V			10	Spe	cial				Reserved for future use
⑦ Thickness	0.85 ± 0.15	mm		1	Pac	kagir	ng			Cardboard Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1M±10% 0.5~5Vrms					
Q	940 min						
Insulation	10,000Mohm or 500Mohm ⋅ μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 $^\circ\!\!\!\mathrm{C}$ to 125 $^\circ\!\!\!\mathrm{C}$, Capacitance change shoud be within ±30PPM/ $^\circ\!\!\!\mathrm{C}$)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance within ±7.5% or ±0.75pF whichever is larger		40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 190 min						
	IR : 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance within $\pm 3\%$ or ± 0.3 pF whichever is large		Max. operating temperature					
	Q : 342.5 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperatur \rightarrow 25 °C					
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^\circ\!$ C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.